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Examiner Signature	<i>H. A. A. A. A.</i>	Date Considered	8/29/2005
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CE11518JGN



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Substitute for form 1449A/PTO  <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)		<i>Complete if Known</i>	
		Application Number	10/758,822
		Filing Date	1/12/2004
		First Named Inventor	VAHID GOUDARZI
		Group Art Unit	2841
		Examiner Name	HOA C. NGUYEN
Sheet 1 of	Attorney Docket No.	CE11518JGN	

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No.¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T²
HN		"lead-Free Mandate Plumbs New Design Challenges" - Schweber, Bill; <a href="http://www.ednmag.com">www.ednmag.com</a> , 4/18/2002	
HN		"Fujitsu Develops Advanced Printing Bump Technology" - Fujitsu Laboratories; <a href="http://pr.fujitsu.com/en/news/2001/12/12-1.html">http://pr.fujitsu.com/en/news/2001/12/12-1.html</a> , 12/12/2001	
HN		"A Constitutive Model for Creep of Lead-Free Solders Undergoing Strain-Enhanced Microstructural Coarsening: A First Report" - Dutta, I; Journal of Electronic Materials, 2002	

Examiner Signature	<i>Hoa Nguyen</i>	Date Considered	8/29/05
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